

Form 1449 (Modified) Information Disclosure Statement By Applicant (Use Several Sheets if Necessary)	Atty Docket No. ALTRP084C1	Application No.: Not yet assigned 101775370
	Applicant: My Nguyen Filing Date February 9, 2004	Group <u>2825</u> Not yet assigned <i>W/H</i>

U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
<i>BA</i>	A1	6,307,160	10.2001	Mei et al.			
<i>BA</i>	A2	6,286,206	09.2001	Li, Chou H.			
<i>BA</i>	A3	6,445,069	09.2002	Ling et al.			
<i>BA</i>	A4	2002/015727	10.2002	Yamamoto, Hidetoshi			

Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
<i>BA</i>	C1	Goyal, et al, "Failure Mechanism of Brittle Solder Joint Fracture in the Presence of Electroless Nickel Immersion Gold (ENIG) Interface", Proceedings of the 52 nd Electronic Component and Technology Conference, 732-739, May 2002.
<i>BA</i>	C2	Binary Alloy Phase Diagrams Binary Alloy Phase Diagrams, 2 nd ed, December 1990, T.B.B. Massalski (Editor), L. Kacprzak (Editor), H. Okamoto (Editor), P.R. Subramanian (Editor), pgs 2269, 2642, 2644, 2294, 2996, 1449, 1451, 1746-1748.
Examiner <i>[Signature]</i>		Date Considered <i>12/22/02</i>

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.